

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-35 (canceled)

Claim 36 (currently amended): An optoelectronic module ~~for use in a fiber optic communications,~~ comprising:

a fiber optics ferrule supporting a set of optical fibers and having a ferrule alignment structure;

an optoelectronic device; and

a silicon substrate carrier adapted to support said optoelectronic device, said silicon substrate carrier including:

a) a plurality of electrically conductive traces for carrying signals to at least one of the optoelectronic device and other devices mounted on said silicon substrate carrier,

b) a carrier alignment structure for cooperating with said ferrule alignment structure and aligning said silicon substrate carrier with said fiber optics ferrule, and

c) at least one alignment mark ~~one or more alignment marks~~ constructed on said silicon substrate carrier and precisely aligned relative to said carrier alignment structure for use in precisely positioning and mounting at least one of the optoelectronic device and the other devices on said silicon substrate carrier, and wherein ~~carrier, and~~

~~the an~~ optoelectronic device comprises ~~comprising~~ a set of photoactive components which is mounted on a the silicon substrate carrier with reference to the at least one alignment mark ~~one or more of said alignment marks~~ so that said optical fibers are aligned with said photoactive components when said silicon substrate carrier is aligned with said fiber optics ferrule.

Claim 37 (currently amended): The optoelectronic module of claim 36, in which:
said ferrule alignment structure comprises a set of alignment holes, and
said carrier alignment structure comprises a set of alignment apertures in said silicon substrate carrier and guide pins extending through said set of alignment apertures.

Claim 38 (currently amended): The optoelectronic module of claim 37, further including:
a support block having at least one support passage ~~one or more support passages~~ formed therein to receive the guide pins for securely supporting said guide pins and said silicon substrate carrier in precisely aligned positions.

Claim 39 (currently amended): The optoelectronic module of claim 36, in which:
said silicon substrate carrier further includes a window section extending through said silicon substrate carrier, and a transparent layer disposed over said window section ~~and one or more alignment marks for precisely positioning devices on said carrier.~~

Claim 40 (currently amended): The optoelectronic module of claim 36, in which:
said photoactive components are arranged in a first linear array, and

said optical fibers are arranged in a second linear array corresponding to said first linear
array of ~~photoactive components~~.

Claim 41 (currently amended): The optoelectronic module of claim 38, wherein:

said guide pins are cemented into said at least one support passage ~~alignment passages~~ of
said support block.

Claim 42 (original): The optoelectronic module of claim 39, further including:

a set of metal traces deposited as a grid on said transparent film layer for use in
suppressing EMI emissions.

Claim 43 (original): The optoelectronic module of claim 38, wherein:

said photoactive components comprise vertical cavity surface-emitting semiconductor
lasers.

Claims 44-50 (canceled)